

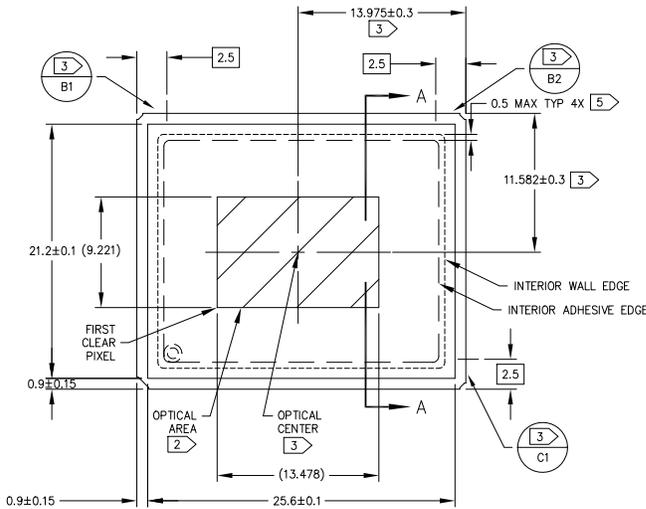
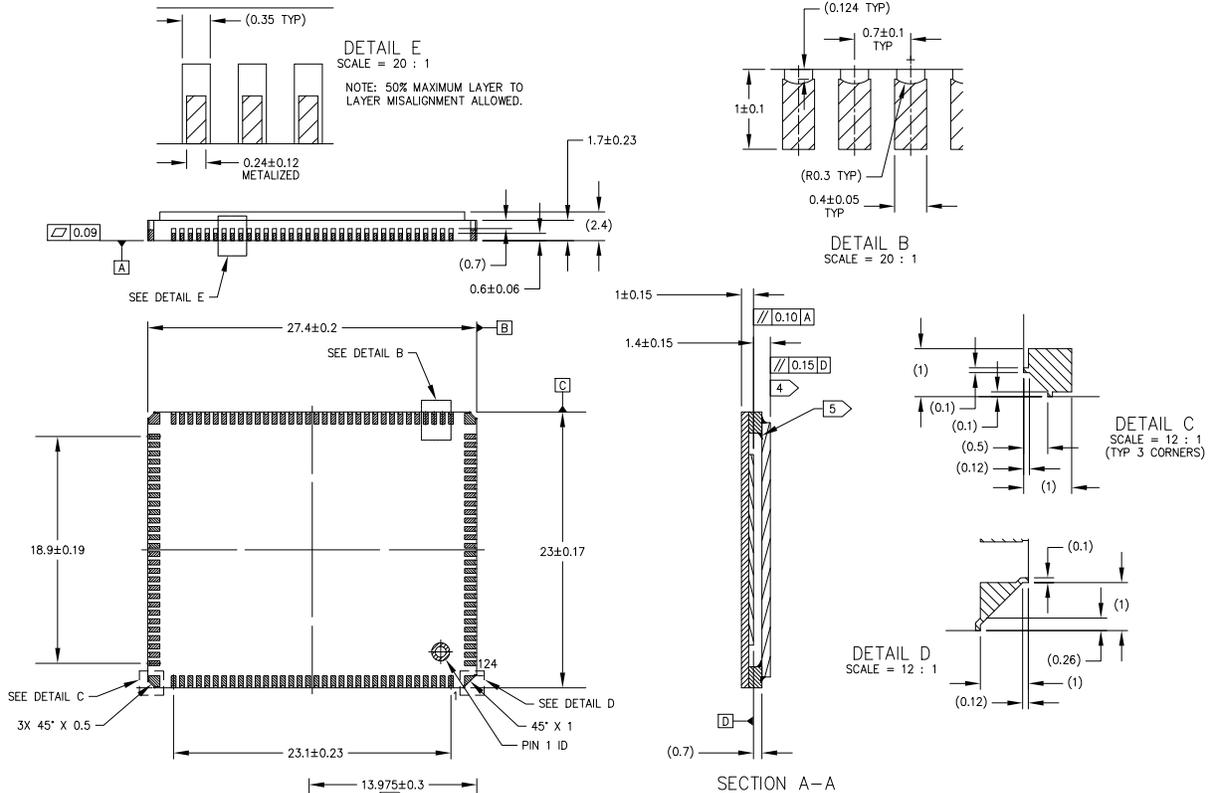
# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



## CLCC124 27.4x23 CASE 848AG ISSUE O

DATE 30 DEC 2014



NOTES	
1	DIMENSIONS IN MM. DIMENSIONS IN ( ) ARE FOR REFERENCE ONLY. DO NOT MEASURE PRINTED DRAWINGS.
2	MAXIMUM ROTATION OF OPTICAL AREA RELATIVE TO DATUMS B1, B2 AND C1: ±0.5°. MAXIMUM FLATNESS OF OPTICAL AREA BETWEEN 0°C AND 50°C: 7 MICRONS.
3	OPTICAL CENTER POSITION DETERMINED WITH RESPECT TO DATUMS B1, B2 AND C1. DATUMS B1, B2 & C1 DETERMINED FROM FLAT AREA 2MM WIDTH X 0.5MM MIN DEPTH.
4	GLASS PARALLELISM APPLIES ONLY TO AREA DIRECTLY ABOVE OPTICAL AREA.
5	GLASS ADHESIVE MATERIAL NOT TO EXTEND BEYOND THE EXTERNAL BOUNDARIES OF THE PACKAGE SEALING AREA.

### GENERIC MARKING DIAGRAM\*



YY = Year  
WW = Work Week

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

<b>DOCUMENT NUMBER:</b>	<b>98AON93124F</b>	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
<b>STATUS:</b>	<b>ON SEMICONDUCTOR STANDARD</b>	
<b>REFERENCE:</b>		
<b>DESCRIPTION:</b>	<b>CLCC124 27.4X23</b>	
		<b>PAGE 1 OF 2</b>

